●USP-11B01 Power Dissipation

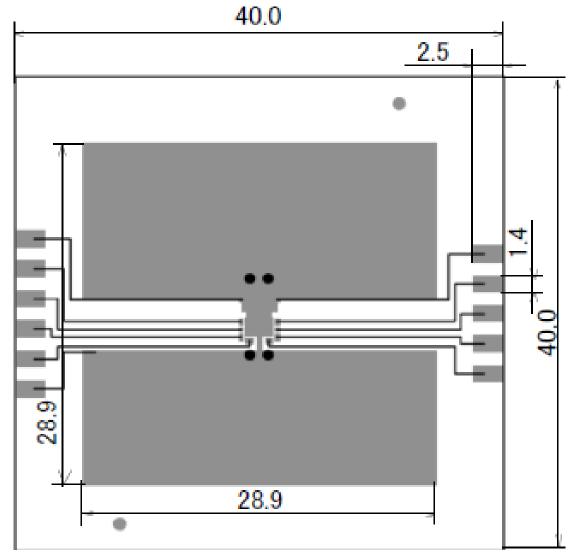
Power dissipation data for the USP-11B01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition

Condition:	Mount on a board
Ambient:	Natural convection
Soldering:	Lead (Pb) free
Board:	Dimensions 40mm×40mm (1600mm^2 in one side)
	Copper (Cu) traces occupy 50% of the board area
	In top and back faces
	Package heat-sink is tied to the copper traces
Material:	Glass Epoxy (FR-4)
Thickness:	1.6mm
Through-hole:	4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	1000	100.00
85	400